



## Final Product Change Notification

202502008F01 : NXP Assembly Site (ATKL) Dicing Process Release as 2nd Source

**Note:** This notice is NXP Company Proprietary.

**Issue Date:** Apr 27, 2025 **Effective Date:** Jul 26, 2025

Dear Lisa Hawkins,

Here is your personalized communication about an NXP notification.  
For detailed information we invite you to [view this notification online](#)

### Management summary

NXP would like to announce the recent addition of capacity for die singulation to now include the NXP assembly and test facility in Kuala Lumpur, Malaysia (ATKL).  
The inclusion of a second location capable of performing this process will help to streamline the supply chain and provide additional internal control to the quality and availability of die used in the affected products listed in this notification.

### Change Category

<input type="checkbox"/> Wafer Fab Process	<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input checked="" type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage

[ ]Firmware [ ]Other

## **Notification Overview**

### **Description**

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NXP would like to announce the recent addition of capacity for die singulation to now include the NXP assembly and test facility in Kuala Lumpur, Malaysia (ATKL).

The inclusion of a second location capable of performing this process will help to streamline the supply chain and provide additional internal control to the quality and availability of die used in the affected products listed in this notification.

### **Reason**

Supply chain flexibility

### **Identification of Affected Products**

Product identification does not change

### **Product Availability**

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### **Sample Information**

Samples are available upon request

### **Production**

Planned first shipment Jul 24, 2025

### **Anticipated Impact on Form, Fit, Function, Reliability or Quality**

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No Impact on form, fit, function, reliability or quality

### **Data Sheet Revision**

No impact to existing data sheet

### **Disposition of Old Products**

NA

### **Additional information**

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Self qualification:[view online](#)

### **Timing and Logistics**

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In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by May 27, 2025.

In compliance with JEDEC J-STD-048, potential Last Time Buy orders shall be placed before Last Time Buy Date.

### **Contact and Support**

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For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.